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[Abstract]

The present invention has been completed to develop a negative photosensitive resin composition that exhibits high refractive index, high transparency properties with no additional post-exposure process, high sensitivity in the exposure, and high resolution and solvent resistance after the pattern formation, and which is capable of providing a pattern having a rectangular cross section adapted for pixel formation and partition formation. Such object is achieved by a negative photosensitive resin composition comprising the following (a) to (d):

(a) metallic compound particles,

(b) a polysiloxane compound,

(c) a compound having at least 1 group containing an α,β-unsaturated carboxylate ester structure, and

(d) a photopolymerization initiator, the composition further comprising

(e) a compound containing maleimide group.